

Electronic Patent Application Fee Transmittal

Application Number:	10565587			
Filing Date:	22-Feb-2007			
Title of Invention:	Copper Foil with Ultra Thin Adhesive Layer, and a Method for Manufacturing the Copper Foil with Ultra Thin Adhesive Layer			
First Named Inventor/Applicant Name:	Tetsuro Sato			
Filer:	Sean Christophe Myers-Payne/Sonja Combest			
Attorney Docket Number:	3209-111			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810